

# MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

Product data sheet  
Product data sheet



SMA

**FEATURES**

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Fast switching for high efficiency
- Low reverse leakage
- Built-in strain relief, ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed: 250°C/10 seconds at terminals

**MECHANICAL DATA**

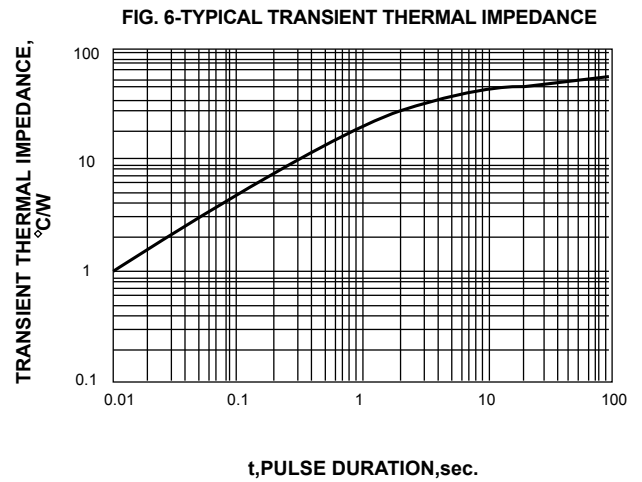
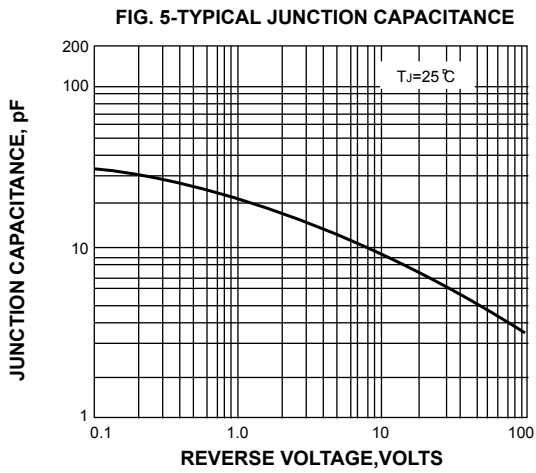
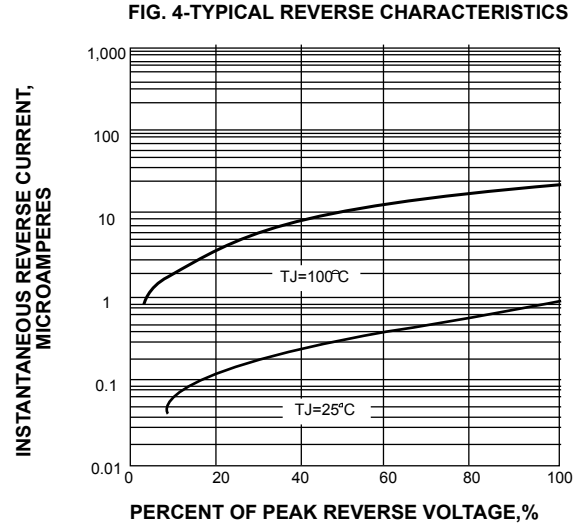
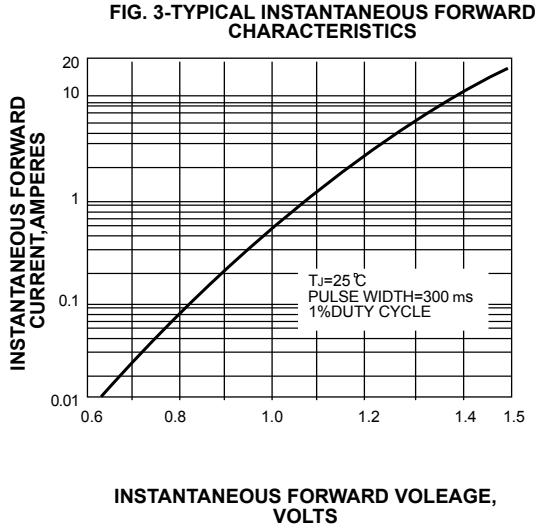
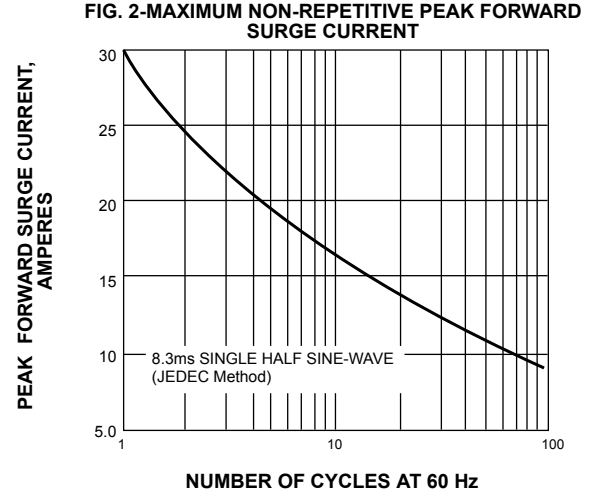
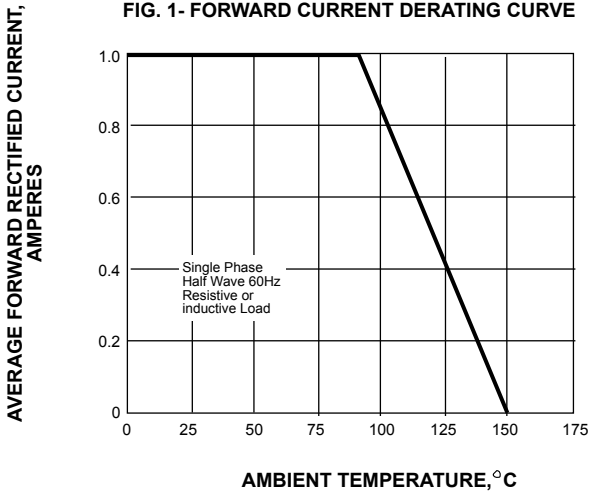
**Case:** JEDEC DO-214AC molded plastic body  
**Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026  
**Polarity:** Color band denotes cathode end  
**Mounting Position:** Any  
**Weight:** 0.003 ounce, 0.093 grams  
 0.004 ounce, 0.111 grams SMA(H)

**MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS**

Ratings at 25°C ambient temperature unless otherwise specified.  
 Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Characteristic	SYMBOLS	RS1A	RS1B	RS1D	RS1G	RS1J	RS1K	RS1M	UNITS
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at $T_L=90^\circ C$	$I_{(AV)}$	1.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	30.0							A
Maximum instantaneous forward voltage at 1.0A	$V_F$	1.3							V
Maximum DC reverse current $T_A=25^\circ C$ at rated DC blocking voltage $T_A=100^\circ C$	$I_R$	5.0 50.0							$\mu A$
Maximum reverse recovery time (NOTE 1)	$t_{rr}$	150				250	500		ns
Typical junction capacitance (NOTE 2)	$C_J$	15.0							pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$	50.0							$^\circ C/W$
Operating junction and storage temperature range	$T_J, T_{STG}$	-65 to +150							$^\circ C$

**Note:** 1.Reverse recovery condition  $I_F=0.5A, I_R=1.0A, I_{rr}=0.25A$   
 2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.  
 3.P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas



**PACKAGE MECHANICAL DATA**



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.65	0.167	0.183
B	2.50	2.90	0.098	0.114
C	1.35	1.65	0.053	0.065
D	0.76	1.52	0.030	0.060
E	4.93	5.28	0.194	0.208
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	1.98	2.41	0.078	0.095
J	6.50		0.256	
K		2.30		0.090
L	1.70		0.067	

**REEL SPECIFICATION**

P/N	PKG	QTY
RS1A THRU RS1M	SMA	2000

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